

Whereas, I/~~we~~ Eiryo TAKASUKA of 1743-1-306 Nagahama, Higashi-Yamashiro-
cho, Imari-shi, Saga, Japan

have invented certain new and useful improvements in TEMPERATURE MEASURING METHOD FOR
SEMICONDUCTOR WAFERS AND PROCESSING APPARATUS for which application for
Letters Patent of the United States of America [] is about to be made ;
[X] has been made

And Whereas, SUMITOMO METAL INDUSTRIES, LTD. of 5-33, 4-chome,
Kitahama, Chuo-ku, Osaka-shi, Osaka, Japan
is desirous of acquiring an interest therein and in the Letters Patent to be obtained
obtained therefor;

Now Therefore, be it known by all whom it may concern, that for and in considera-
tion of the sum of ten dollars (\$10.00) and other valuable consideration to me/~~us~~ in
hand paid, the receipt of which is hereby acknowledged I/~~we~~ have assigned, sold, and
set over, and by these presents do assign, sell, and set over unto the said
SUMITOMO METAL INDUSTRIES, LTD.

for the territory of the United States of America, and not elsewhere; the full and
exclusive right, title, and interest in and to the said invention, as fully set forth
and described in the specification

[] prepared and executed by me/us on _____
[X] filed in the U.S. Patent Office under Serial No. 09/234,368 on January 21, 1999
preparatory to obtaining Letters Patent therefor; said invention, application and
Letters Patent to be held and enjoyed by the said SUMITOMO METAL INDUSTRIES, LTD.

_____ to the full end of the
term for which said Letters Patent are granted, as fully and entirely as the same
would have been held by me/~~us~~ had this assignment and sale not been made.

INVENTOR(S):

DATE:

Eiryo Takasuka
Eiryo TAKASUKA

Feb. 2nd, 1999